



ALPHA & OMEGA
SEMICONDUCTOR, INC.

Nov 2002

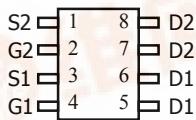
AO4604 Complementary Enhancement Mode Field Effect Transistor

General Description

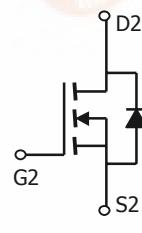
The AO4604 uses advanced trench technology MOSFETs to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in power inverters, and other applications.

Features

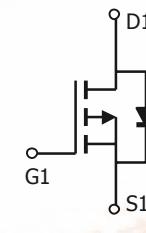
n-channel	p-channel
V_{DS} (V) = 30V	-30V
I_D = 6.9A	-5A
$R_{DS(ON)}$	$R_{DS(ON)}$
< 28mΩ (V_{GS} =10V)	< 52mΩ (V_{GS} = 10V)
< 42mΩ (V_{GS} =4.5V)	< 87mΩ (V_{GS} = 4.5V)



SOIC-8



n-channel



p-channel

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current ^A	I_D	6.9	-5	A
$T_A=70^\circ\text{C}$		5.8	-4.2	
Pulsed Drain Current ^B	I_{DM}	30	-20	
Power Dissipation	P_D	2	2	W
$T_A=70^\circ\text{C}$		1.44	1.44	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics: n-channel and p-channel

Parameter	Symbol	Device	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	n-ch	48	62.5	°C/W
Steady-State		n-ch	74	110	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	n-ch	35	40	°C/W
Steady-State		p-ch	48	62.5	°C/W
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	p-ch	74	110	°C/W
Steady-State		p-ch	35	40	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	p-ch	48	62.5	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted): N-CHANNEL

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.9	3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	20			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=6.9\text{A}$ $T_J=125^\circ\text{C}$		22.5 31.3	28 38	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=5.0\text{A}$		34.5	42	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=6.9\text{A}$	10	15.4		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$		0.76	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		680		pF
C_{oss}	Output Capacitance			102		pF
C_{rss}	Reverse Transfer Capacitance			77		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		3		Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=6.9\text{A}$		13.84		nC
$Q_g(4.5\text{V})$	Total Gate Charge			6.74		nC
Q_{gs}	Gate Source Charge			1.82		nC
Q_{gd}	Gate Drain Charge			3.2		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=2.2\Omega, R_{\text{GEN}}=3\Omega$		4.6		ns
t_r	Turn-On Rise Time			4.1		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			20.6		ns
t_f	Turn-Off Fall Time			5.2		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=6.9\text{A}, dI/dt=100\text{A}/\mu\text{s}$		16.5		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=6.9\text{A}, dI/dt=100\text{A}/\mu\text{s}$		7.8		nC

A: The value of $R_{\theta,\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta,\text{JA}}$ is the sum of the thermal impedance from junction to lead $R_{\theta,\text{JL}}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted): P-CHANNEL

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1	μA
					-5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1	-1.8	-3	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$	-10			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=5.0\text{A}$ $T_J=125^\circ\text{C}$		39	52	$\text{m}\Omega$
				54	70	
		$V_{GS}=-4.5\text{V}, I_D=4\text{A}$		67	87	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-5\text{A}$	6	8.6		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.77	-1	V
I_S	Maximum Body-Diode Continuous Current				-2.8	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		700		pF
C_{oss}	Output Capacitance			120		pF
C_{rss}	Reverse Transfer Capacitance			75		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		10		Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=5\text{A}$		14.7		nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			7.6		nC
Q_{gs}	Gate Source Charge			2		nC
Q_{gd}	Gate Drain Charge			3.8		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=3\Omega, R_{\text{GEN}}=3\Omega$		8.3		ns
t_r	Turn-On Rise Time			5		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			29		ns
t_f	Turn-Off Fall Time			14		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		23.5		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		13.4		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

N-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

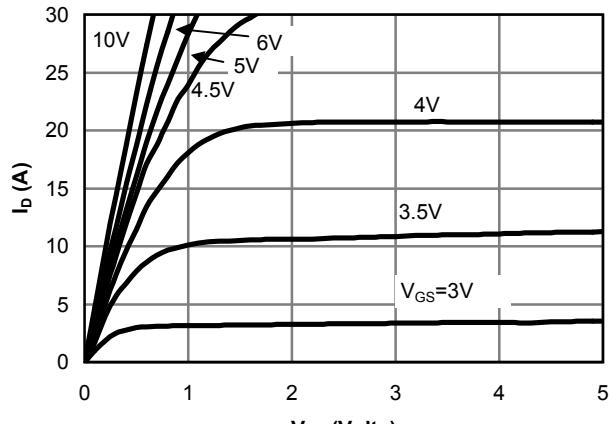


Fig 1: On-Region Characteristics

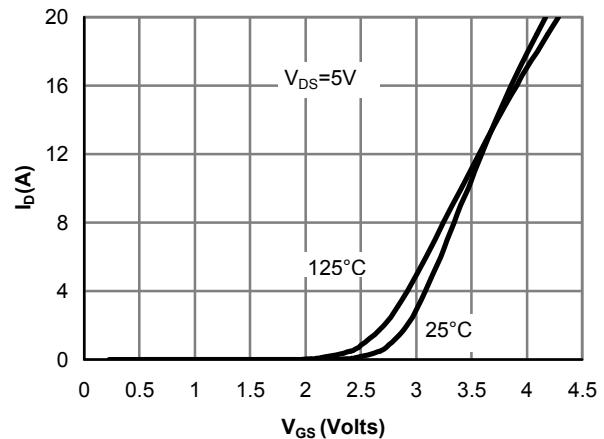


Figure 2: Transfer Characteristics

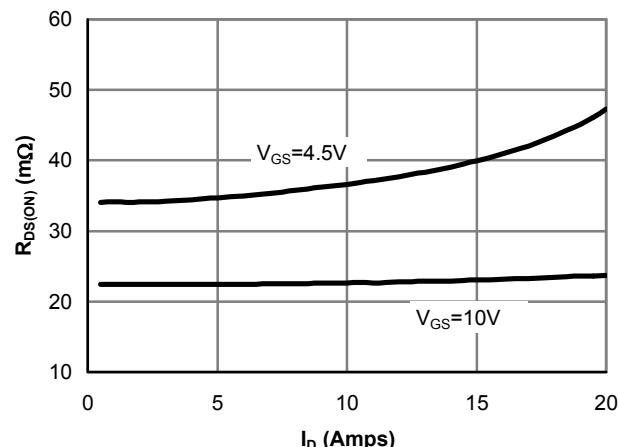


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

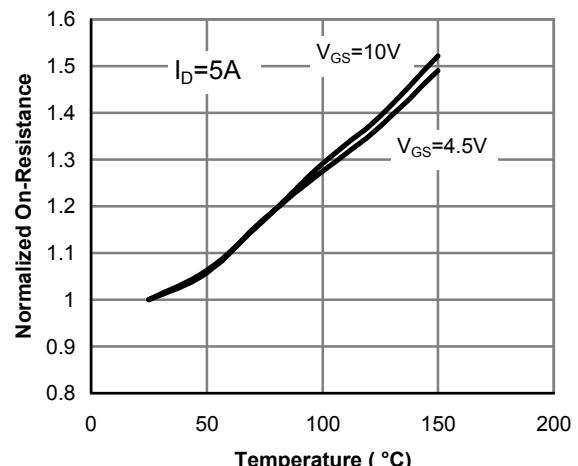


Figure 4: On-Resistance vs. Junction Temperature

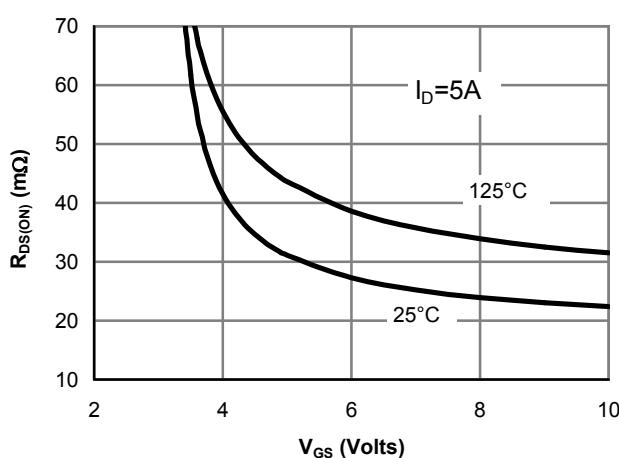


Figure 5: On-Resistance vs. Gate-Source Voltage

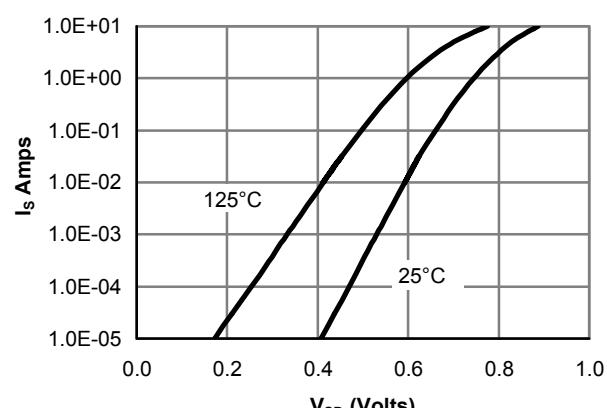


Figure 6: Body diode characteristics

N-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

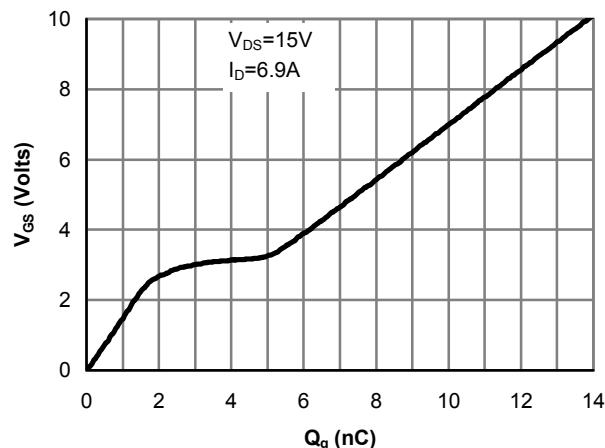


Figure 7: Gate-Charge characteristics

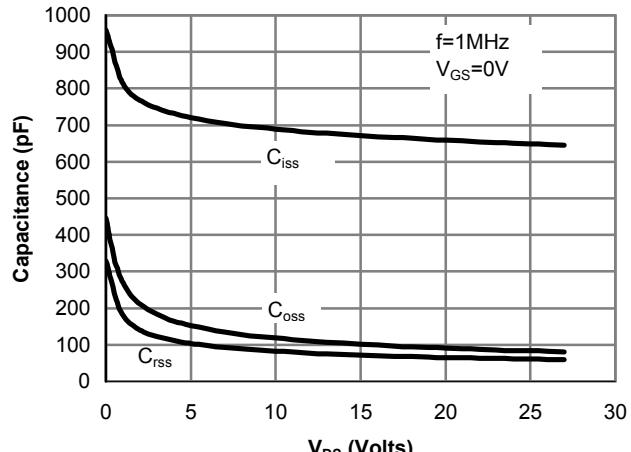


Figure 8: Capacitance Characteristics

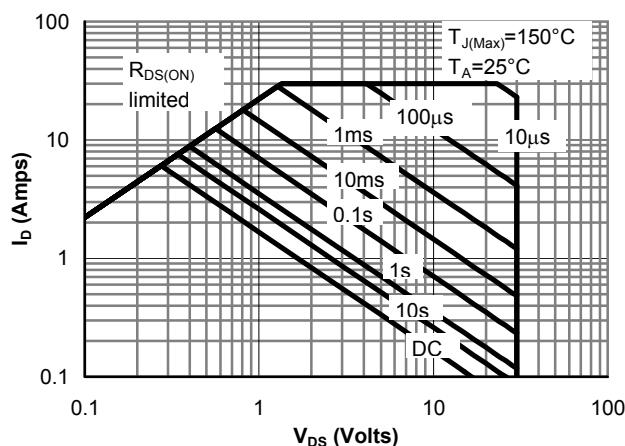


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

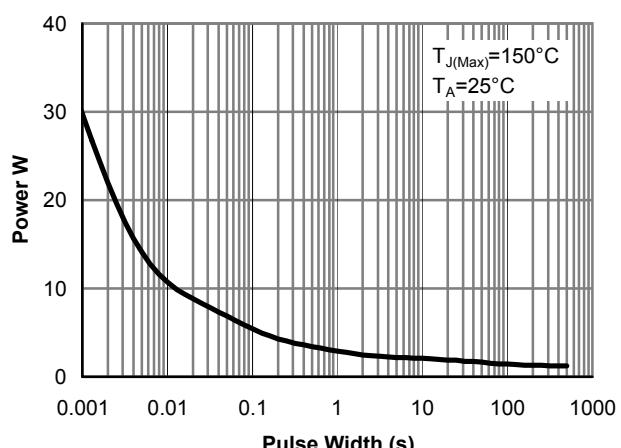


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

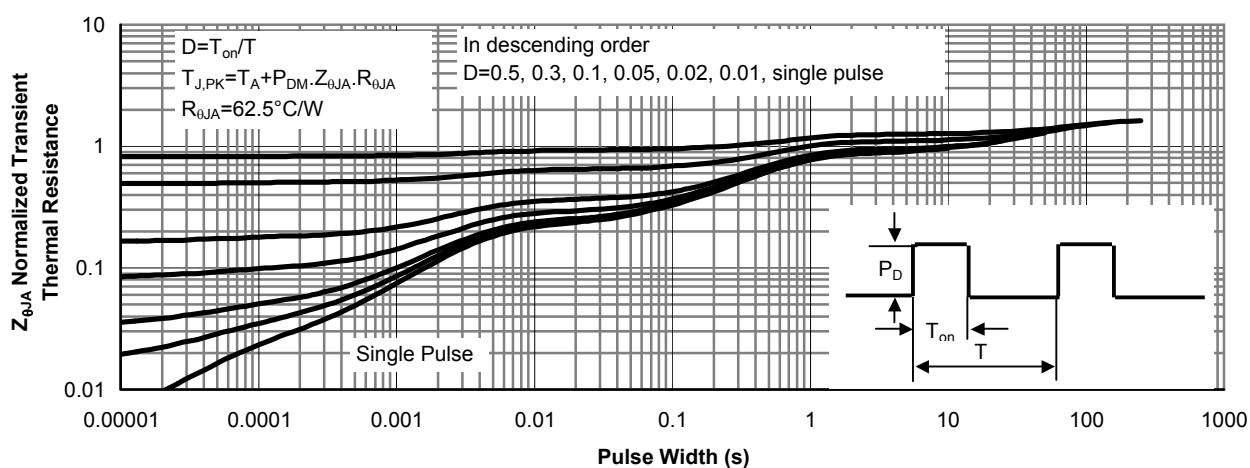


Figure 11: Normalized Maximum Transient Thermal Impedance

P-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

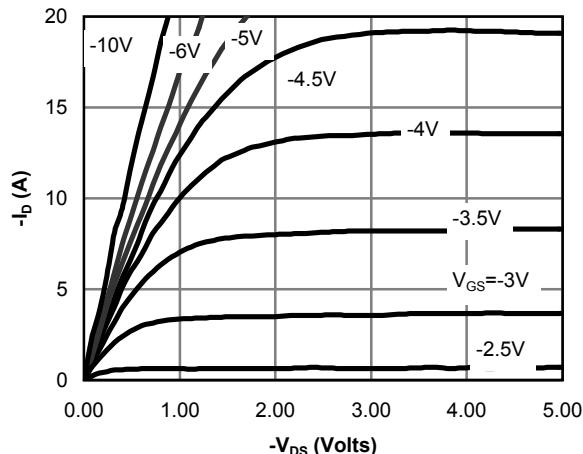


Figure 1: On-Region Characteristics

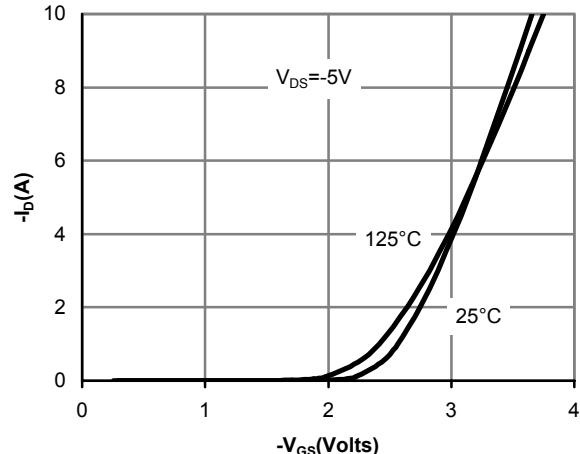


Figure 2: Transfer Characteristics

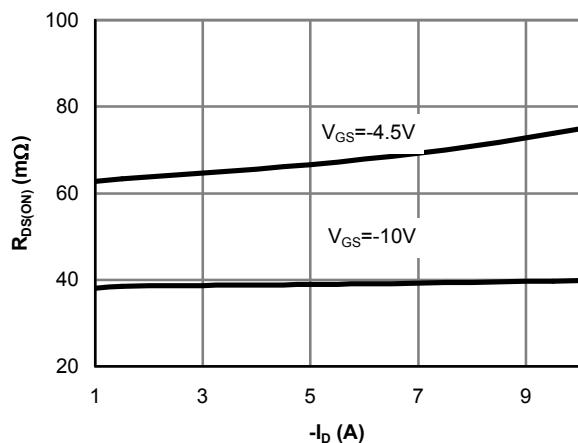


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

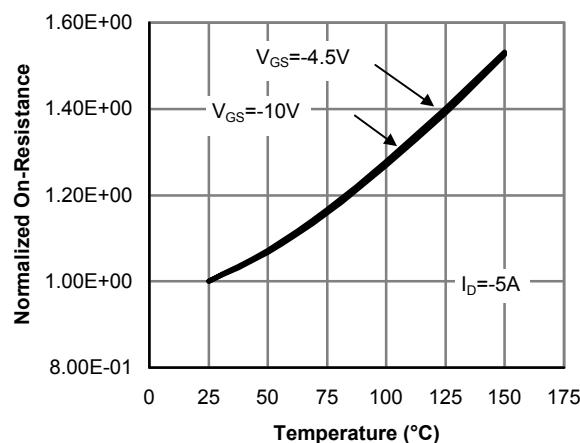


Figure 4: On-Resistance vs. Junction Temperature

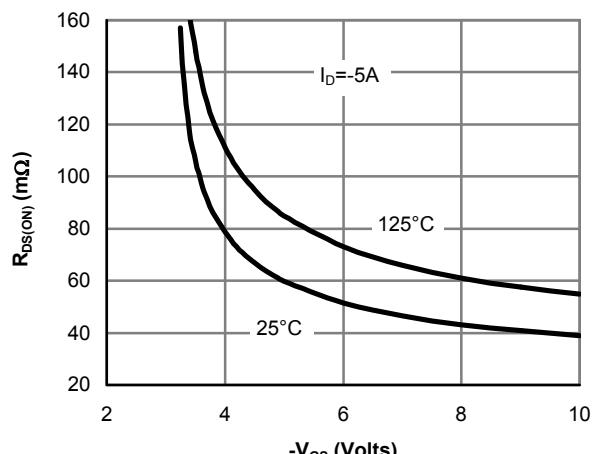


Figure 5: On-Resistance vs. Gate-Source Voltage

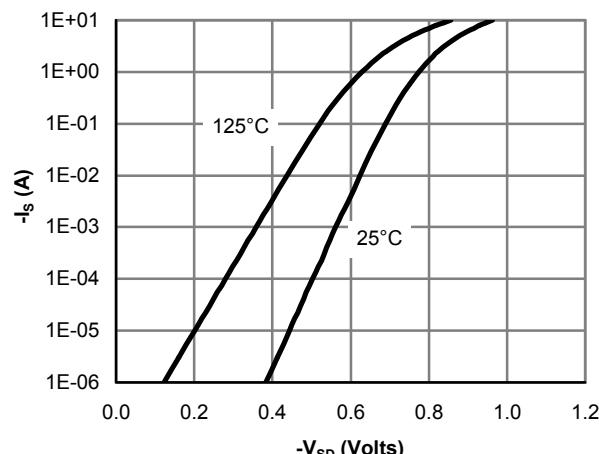


Figure 6: Body-Diode Characteristics

P-CHANNEL TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

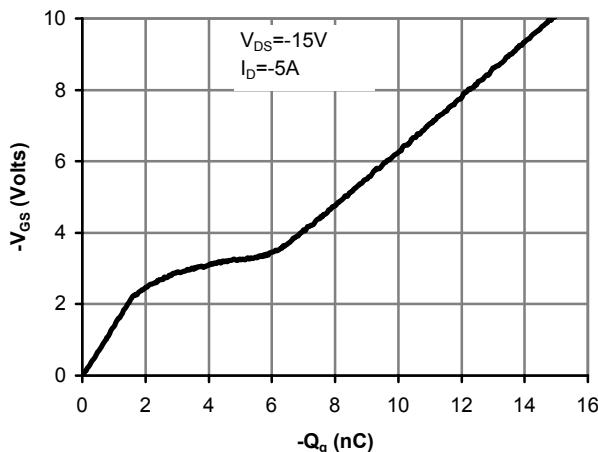


Figure 7: Gate-Charge Characteristics

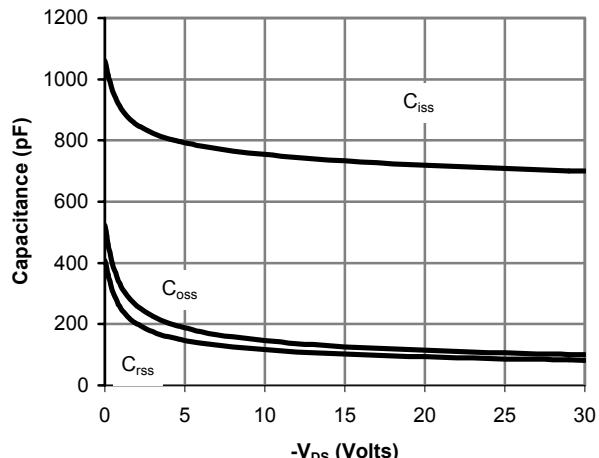


Figure 8: Capacitance Characteristics

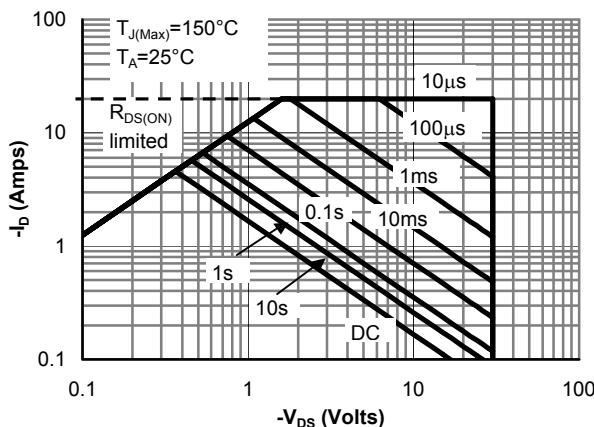


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

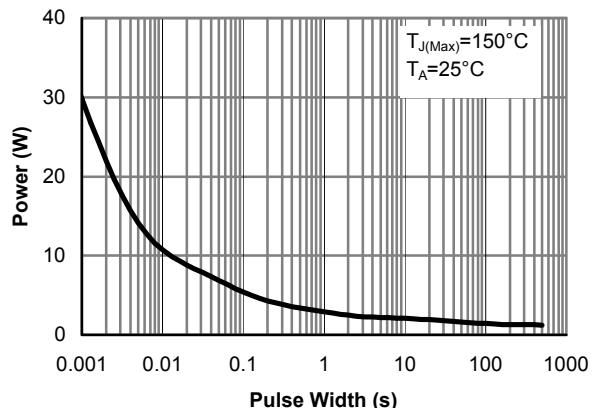


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

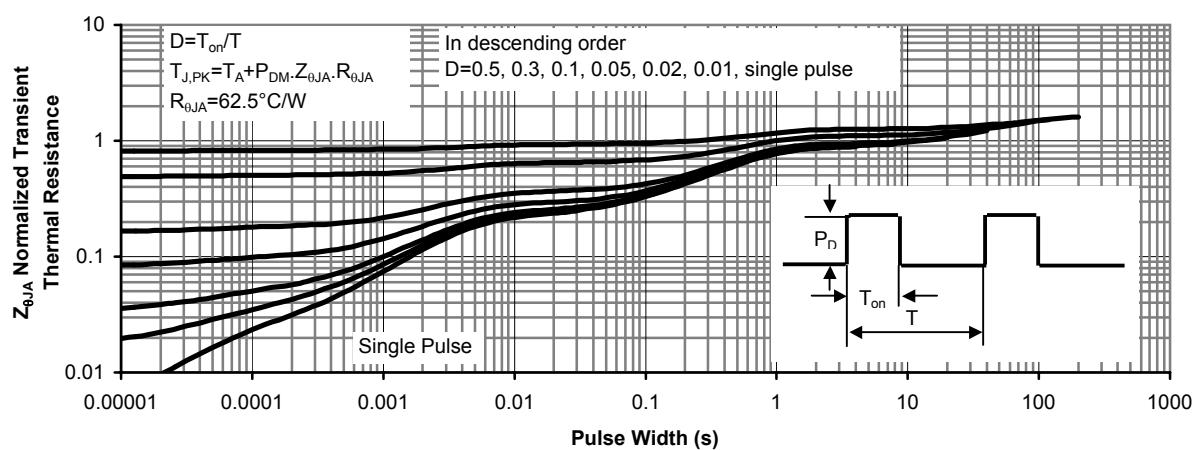
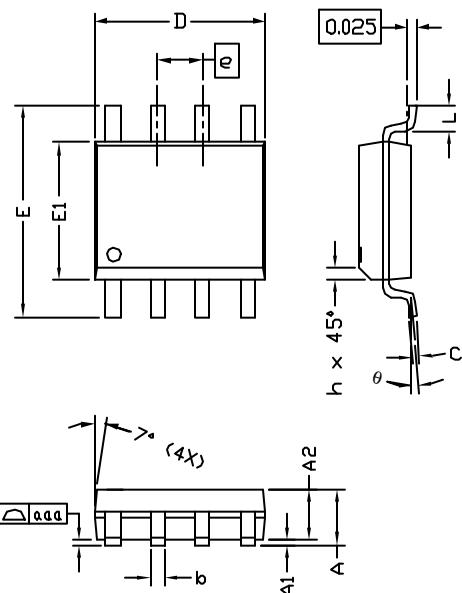


Figure 11: Normalized Maximum Transient Thermal Impedance



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SO-8 Package Data

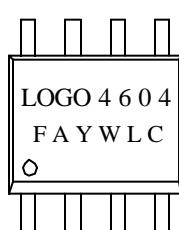


SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.45	1.50	1.55	0.057	0.059	0.061
A1	0.00	—	0.10	0.000	—	0.004
A2	—	1.45	—	—	0.057	—
b	0.33	—	0.51	0.013	—	0.020
c	0.19	—	0.25	0.007	—	0.010
D	4.80	—	5.00	0.189	—	0.197
E1	3.80	—	4.00	0.150	—	0.157
e	1.27 BSC			0.050 BSC		
E	5.80	—	6.20	0.228	—	0.244
h	0.25	—	0.50	0.010	—	0.020
L	0.40	—	1.27	0.016	—	0.050
aaa	—	—	0.10	—	—	0.004
θ	0°	—	8°	0°	—	8°

NOTE:

1. LEAD FINISH: 150 MICROINCHES (3.8 um) MIN.
THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD
2. TOLERANCE ± 0.10 mm (4 mil) UNLESS OTHERWISE
SPECIFIED
3. COPLANARITY : 0.10 mm
4. DIMENSION L IS MEASURED IN GAGE PLANE

PACKAGE MARKING DESCRIPTION

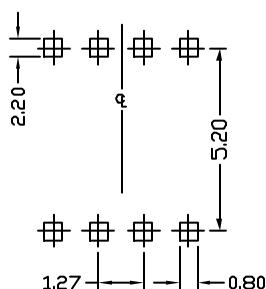


NOTE:
 LOGO - AOS LOGO
 4604 - PART NUMBER CODE.
 F - FAB LOCATION
 A - ASSEMBLY LOCATION
 Y - YEAR CODE
 W - WEEK CODE.
 L C - ASSEMBLY LOT CODE

SOP-8 PART NO. CODE

PART NO.	CODE
AO4604	4604

RECOMMENDED LAND PATTERN



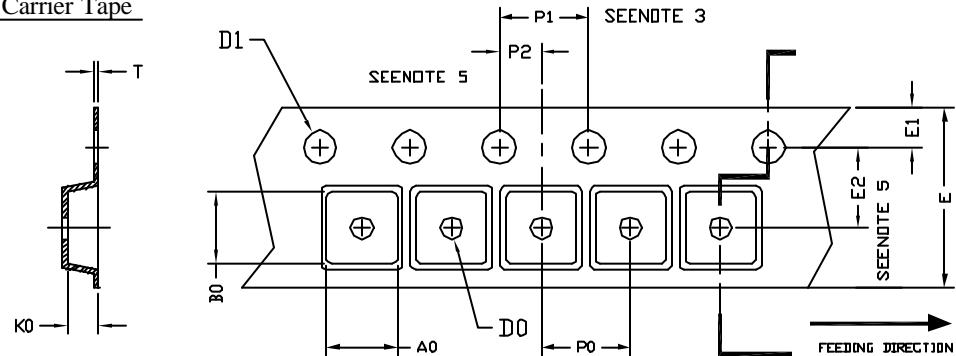
UNIT: mm



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SO-8 Tape and Reel Data

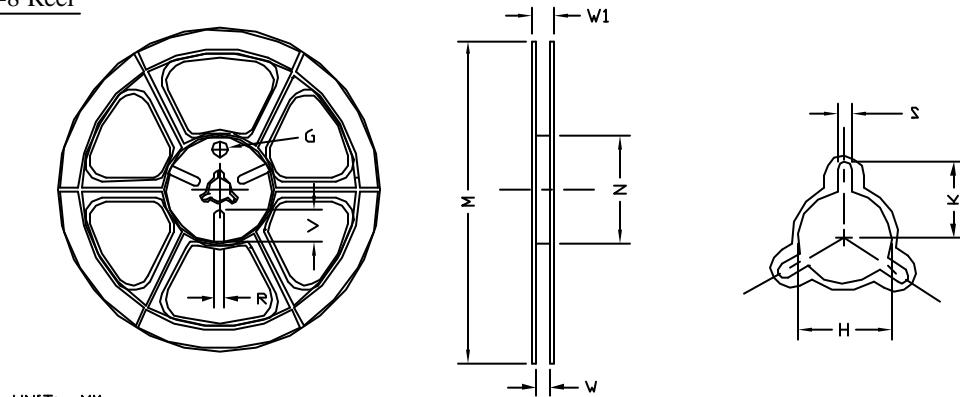
SO-8 Carrier Tape



UNIT: MM

PACKAGE	A_0	B_0	K_0	D_0	D_1	E	E_1	E_2	P_0	P_1	P_2	T
SO-8 (12 mm)	6.40 ± 0.10	5.20 ± 0.10	2.10 ± 0.10	1.60 ± 0.10	1.30 ± 0.10	12.00 ± 0.30	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.25 ± 0.05

SO-8 Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W_1	H	K	S	G	R	V
12 mm	$\phi 330$	$\phi 330.00$ ± 0.50	$\phi 97.00$ ± 0.10	13.00 ± 0.30	17.40 ± 1.00	$\phi 13.00$ $+0.50$ -0.20	10.60	2.00 ± 0.50	---	---	---

SO-8 Tape

Leader / Trailer
& Orientation

